## SURFACE MOUNT HIGH EFFICIENCY RECTIFIER REVERSE VOLTAGE 50 to 1000 Volts FORWARD CURRENT 2.0 Ampere

## FEATURES

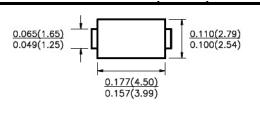
Plastic package has UL flammability Classification 94V-0 Glass Passivated chip junction Built in strain relief Fast switching speed for high efficiency High temperature soldering guaranteed: 250°C/10 seconds

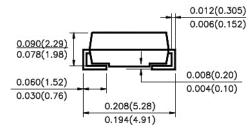
### **MECHANICAL DATA**

Case: JEDED DO-214AC transfer molded plastic Terminals: Solder plated, Solderable per MIL-STD-750, Method 2026 Polarity: Color band denotes cathode end

# DO-214AC (SMA)

US2A THRU





#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified, Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load derate current by 20%

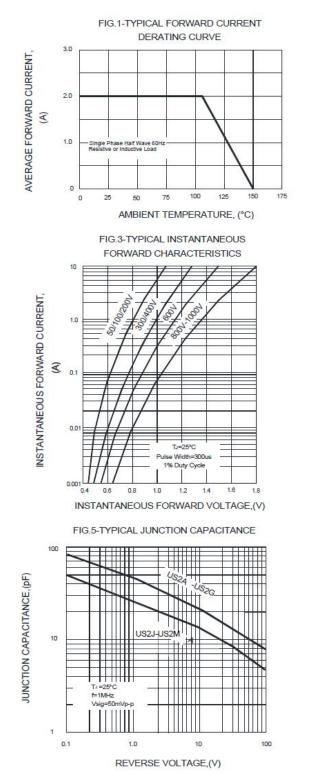
PARAMETER		SYMBOL	US2A	US2B	US2D	US2G	US2J	US2K	US2M	UNIT
Maximum Repetitive Peak Reverse Voltage		Vrrm	50	100	200	400	600	800	1000	VOLTS
Maximum RMS Voltage		Vrms	35	70	140	280	420	560	700	VOLTS
Maximum DC Blocking Voltage		Vdc	50	100	200	400	600	800	1000	VOLTS
Maximum Average Forward Rectified Current At $T_L = 90^{\circ}C$ (NOTE 1)		I(AV)	2.0						Amps	
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)		IFSM	50						Amps	
Maximum instantaneous forward voltage at 2.0A		VF	1.0 1.3 1.7					VOLTS		
Maximum DC Reverse Current at Rated DC blocking voltage	T <sub>A</sub> =25℃		5.0							– uA
	T <sub>A</sub> =125℃	l <sub>R</sub>	100							
Maximum Reverse Recovery Time Test conditions I <sub>F</sub> =0.5A, I <sub>R</sub> =1.0A, I <sub>RR</sub> =0.25A		t <sub>rr</sub>		50	75				ns	
Typical Junction Capacitance(Measured at 1.0MHz and applied reverse voltage of 4.0V)		CJ		50		30				pF
Typical Thermal Resistance (NOTE 1)		Reja	50							°CW
		Rej∟	17							
Operating Junction Temperature		TJ	-55 to +150							°C
Storage Temperature Rang		Тѕтс	-55 to +150							°C
1. Thermal resistance from lunction to embient and from junction to load mounted on $D \cap D$ , with $0.2 \times 0.2^{\prime\prime}$ (5.0 \times 5.0 mm).										

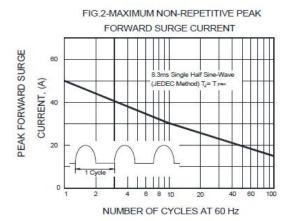
1- Thermal resistance from Junction to ambient and from junction to lead mounted on P.C.B. with  $0.2 \times 0.2''$  ( $5.0 \times 5.0$ mm) copper pad areas.

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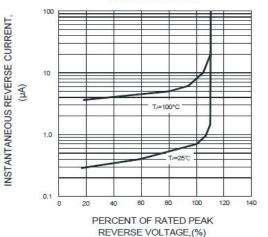
# **RATINGS AND CHARACTERISTIC CURVES**



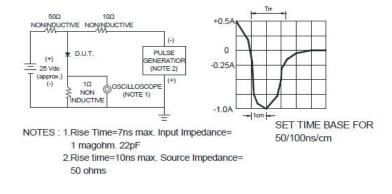


**US2A THRU US2N** 

FIG.4-TYPICAL REVERSE CHARACTERISTICS







Note: Specifications are subject to change without notice.

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